Exhibit 13 - APPENDIX D
HAC T-Coil Data Plots

Z (AXIAL) MEASUREMENT: CDMA 800 Channel 1013
Equipment Setting:

DUT: SCP-2700;   Type: Cellular Phone ;   Serial Number: 0450;   **Date:** 12/11/2008
Communication System: CDMA; Frequency: 824.7 MHz;Duty Cycle: 1:1
Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH1013/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -7.46 dB A/m
BWC Factor = 0.0105903 dB
Location: 3, -5, 363.7 mm

Scans CH1013/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -5.37 dB A/m
BWC Factor = 0.0105903 dB
Location: -0.2, -5, 363.7 mm

Point meas,TCoil on CH1013/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -4.96 dB A/m
BWC Factor = 0.0105036 dB
Location: -1, -5, 363.7 mm

Point meas,TCoil on CH1013/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -42.6 dB A/m
Location: -1, -5, 363.7 mm

Point meas,TCoil on CH1013/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):
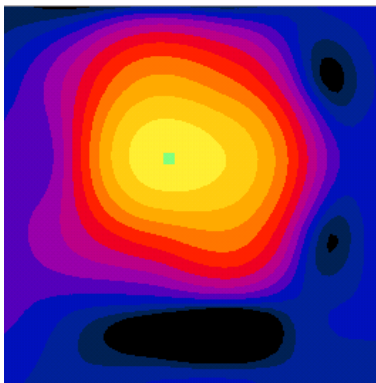Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1/ABM2 = 37.7 dB
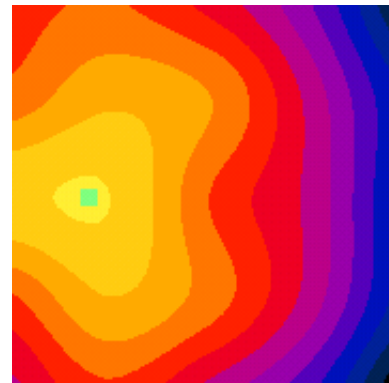ABM1 comp = -4.96 dB A/m
BWC Factor = 0.0105036 dB
Location: -1, -5, 363.7 mm

Z (axial) rough 50x50 scan:

0 dB = 1.00A/m

Z (axial) 16x16scan:

0 dB = 1.00A/m

X RADIAL MEASUREMENT: CDMA 800 Channel 1013

Equipment Setting:

DUT: SCP-2700;   Type: Cellular Phone ;   Serial Number: 0450;   **Date:** 12/11/2008
Communication System: CDMA; Frequency: 824.7 MHz;Duty Cycle: 1:1
Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH1013/x (longitudinal) 24 x 16/ABM Interpolated Signal(x,y,z) (61x41x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -12.6 dB A/m
BWC Factor = 0.0105903 dB
Location: -7.8, -5.4, 363.7 mm

Point meas,TCoil on CH1013/x (longitudinal) at max x/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -14.9 dB A/m
BWC Factor = 0.0105036 dB
Location: 11, -9, 363.7 mm

Point meas,TCoil on CH1013/x (longitudinal) at max x/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -50.9 dB A/m
Location: 11, -9, 363.7 mm

Point meas,TCoil on CH1013/x (longitudinal) at max x/ABM SNR(x,y,z) (1x1x1):
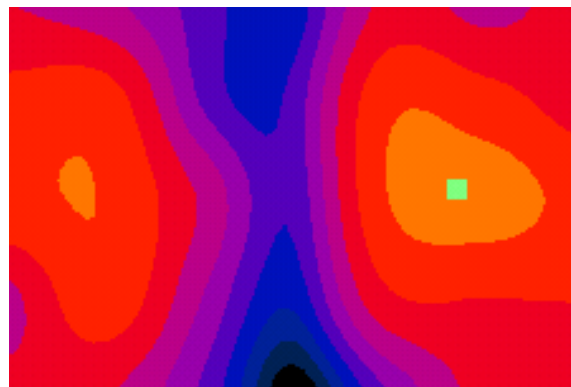Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1/ABM2 = 36.0 dB
ABM1 comp = -14.9 dB A/m
BWC Factor = 0.0105036 dB

X (Radial) 24x16 scan:

0 dB = 1.00A/m

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Y RADIAL MEASUREMENT: CDMA 800 Channel 1013

Equipment Setting:

DUT: SCP-2700;   Type: Cellular Phone ;   Serial Number: 0450;   **Date:** 12/11/2008
Communication System: CDMA; Frequency: 824.7 MHz;Duty Cycle: 1:1
Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH1013/y (transversal) 16 x 24/ABM Interpolated Signal(x,y,z) (41x61x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -13.2 dB A/m
BWC Factor = 0.0105903 dB
Location: 0.6, -13, 363.7 mm

Point meas,TCoil on CH1013/y (transversal) at max y/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -15.8 dB A/m
BWC Factor = 0.0105036 dB
Location: -5, 7, 363.7 mm

Point meas,TCoil on CH1013/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -57.3 dB A/m
Location: -5, 7, 363.7 mm

Point meas,TCoil on CH1013/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):
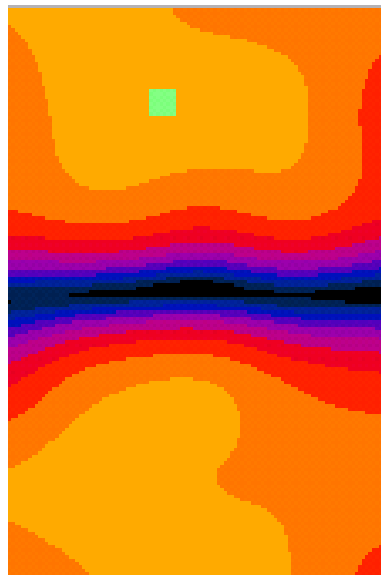Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1/ABM2 = 41.5 dB
ABM1 comp = -15.8 dB A/m
BWC Factor = 0.0105036 dB
Location: -5, 7, 363.7 mm

Y (Radial) 16x24 scan:

0 dB = 1.00A/m

Z (AXIAL) MEASUREMENT: CDMA 800 Channel 383

Equipment Setting:

DUT: SCP-2700;   Type: Cellular Phone ;   Serial Number: 0450;   **Date:** 12/11/2008
008 Communication System: CDMA; Frequency: 836.49 MHz;Duty Cycle: 1:1
Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH383/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -6.11 dB A/m
BWC Factor = 0.0106771 dB
Location: 1, -5, 363.7 mm

Scans CH383/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -5.79 dB A/m
BWC Factor = 0.0106771 dB
Location: -0.2, -9, 363.7 mm

Point meas,TCoil on CH383/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -5.65 dB A/m
BWC Factor = 0.0105036 dB
Location: -1, -9, 363.7 mm

Point meas,TCoil on CH383/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -43.5 dB A/m
Location: -1, -9, 363.7 mm

Point meas,TCoil on CH383/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):
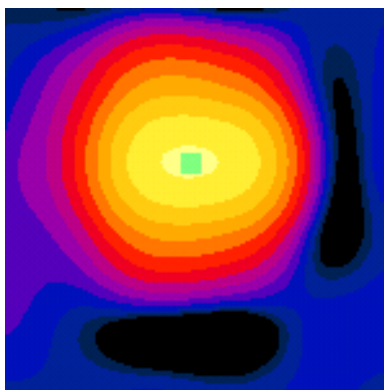Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1/ABM2 = 37.8 dB
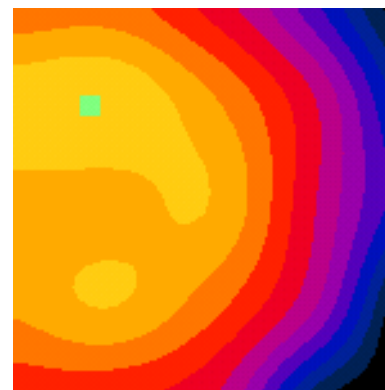ABM1 comp = -5.65 dB A/m
BWC Factor = 0.0105036 dB
Location: -1, -9, 363.7 mm

Z (axial) rough 50x50 scan:

0 dB = 1.00A/m

Z (axial) 16x16scan:

0 dB = 1.00A/m

HAC T-Coil Plots   Model: SCP-2700

X RADIAL MEASUREMENT: CDMA 800 Channel 383

Equipment Setting:

DUT: SCP-2700;   Type: Cellular Phone ;   Serial Number: 0450;   **Date:** 12/11/2008
008 Communication System: CDMA; Frequency: 836.49 MHz;Duty Cycle: 1:1
Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH383/x (longitudinal) 24 x 16/ABM Interpolated Signal(x,y,z) (61x41x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -12.6 dB A/m
BWC Factor = 0.0106771 dB
Location: -9.4, -9, 363.7 mm

Point meas,TCoil on CH383/x (longitudinal) at max x/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -12.8 dB A/m
BWC Factor = 0.0105036 dB
Location: -9, -9, 363.7 mm

Point meas,TCoil on CH383/x (longitudinal) at max x/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
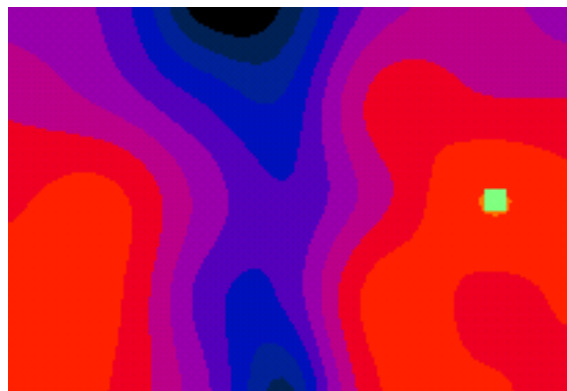ABM2 = -46.4 dB A/m
Location: -9, -9, 363.7 mm

Point meas,TCoil on CH383/x (longitudinal) at max x/ABM SNR(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1/ABM2 = 33.6 dB
ABM1 comp = -12.8 dB A/m
BWC Factor = 0.0105036 dB
Location: -9, -9, 363.7 mm

X (Radial) 24x16 scan:

0 dB = 1.00A/m

Y RADIAL MEASUREMENT: CDMA 800 Channel 383

Equipment Setting:

DUT: SCP-2700;   Type: Cellular Phone ;   Serial Number: 0450;   **Date:** 12/11/2008
008 Communication System: CDMA; Frequency: 836.49 MHz;Duty Cycle: 1:1
Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH383/y (transversal) 16 x 24/ABM Interpolated Signal(x,y,z) (41x61x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -12.6 dB A/m
BWC Factor = 0.0106771 dB
Location: 3, -13.8, 363.7 mm

Point meas,TCoil on CH383/y (transversal) at max y/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -14.8 dB A/m
BWC Factor = 0.0105036 dB
Location: -5, 3, 363.7 mm

Point meas,TCoil on CH383/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -55.6 dB A/m
Location: -5, 3, 363.7 mm

Point meas,TCoil on CH383/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):
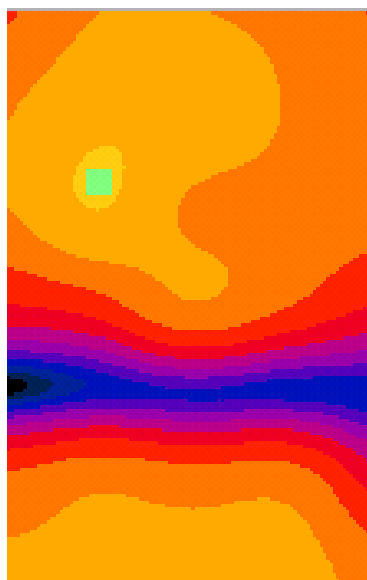Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1/ABM2 = 40.8 dB
ABM1 comp = -14.8 dB A/m
BWC Factor = 0.0105036 dB
Location: -5, 3, 363.7 mm

Y (Radial) 16x24 scan:

0 dB = 1.00A/m

Z (AXIAL) MEASUREMENT: CDMA 800 Channel 777

Equipment Setting:

DUT: SCP-2700;   Type: Cellular Phone ;   Serial Number: 0450;   **Date:** 12/11/2008
Communication System: CDMA; Frequency: 848.31 MHz;Duty Cycle: 1:1
Medium parameters used: $\sigma = 0$ mho/m, $\varepsilon_r = 1$; $\rho = 0$ kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH777/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -6.39 dB A/m
BWC Factor = 0.0109373 dB
Location: 3, -5, 363.7 mm

Scans CH777/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -4.97 dB A/m
BWC Factor = 0.0109373 dB
Location: -0.6, -5, 363.7 mm

Point meas,TCoil on CH777/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -4.99 dB A/m
BWC Factor = 0.0103301 dB
Location: -1, -5, 363.7 mm

Point meas,TCoil on CH777/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -42.1 dB A/m
Location: -1, -5, 363.7 mm

Point meas,TCoil on CH777/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):
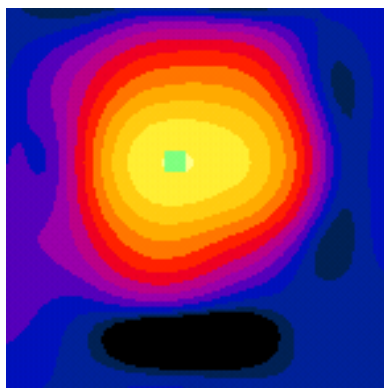Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1/ABM2 = 37.1 dB
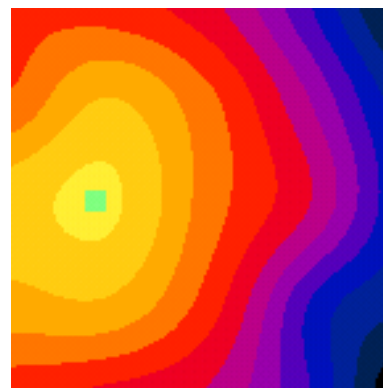ABM1 comp = -4.99 dB A/m
BWC Factor = 0.0103301 dB
Location: -1, -5, 363.7 mm

Z (axial) rough 50x50 scan:

0 dB = 1.00A/m

Z (axial) 16x16scan:

0 dB = 1.00A/m

X RADIAL MEASUREMENT: CDMA 800 Channel 777

Equipment Setting:

DUT: SCP-2700;   Type: Cellular Phone ;   Serial Number: 0450;   **Date:** 12/11/2008
Communication System: CDMA; Frequency: 848.31 MHz;Duty Cycle: 1:1
Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH777/x (longitudinal) 24 x 16/ABM Interpolated Signal(x,y,z) (61x41x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -12.1 dB A/m
BWC Factor = 0.0109373 dB
Location: -9.4, -5, 363.7 mm

Point meas,TCoil on CH777/x (longitudinal) at max x/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -14.5 dB A/m
BWC Factor = 0.0103301 dB
Location: 11, -9, 363.7 mm

Point meas,TCoil on CH777/x (longitudinal) at max x/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -50.6 dB A/m
Location: 11, -9, 363.7 mm

Point meas,TCoil on CH777/x (longitudinal) at max x/ABM SNR(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
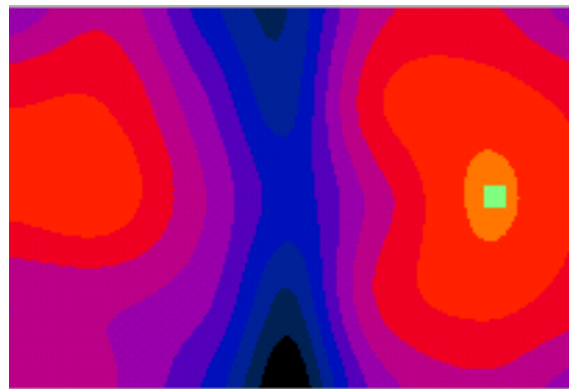**Cursor:**
ABM1/ABM2 = 36.1 dB
ABM1 comp = -14.5 dB A/m
BWC Factor = 0.0103301 dB
Location: 11, -9, 363.7 mm

X (Radial) 24x16 scan:

0 dB = 1.00A/m

Y RADIAL MEASUREMENT: CDMA 800 Channel 777

Equipment Setting:

DUT: SCP-2700;   Type: Cellular Phone ;   Serial Number: 0450;   Date: 012/11/2008
Communication System: CDMA; Frequency: 848.31 MHz;Duty Cycle: 1:1
Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH777/y (transversal) 16 x 24/ABM Interpolated Signal(x,y,z) (41x61x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -13.3 dB A/m
BWC Factor = 0.0109373 dB
Location: -0.2, -13, 363.7 mm

Point meas,TCoil on CH777/y (transversal) at max y/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -14.8 dB A/m
BWC Factor = 0.0105036 dB
Location: -5, 3, 363.7 mm

Point meas,TCoil on CH777/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -55.6 dB A/m
Location: -5, 3, 363.7 mm

Point meas,TCoil on CH777/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):
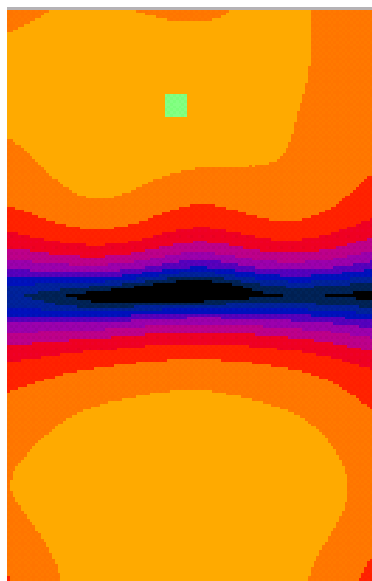Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1/ABM2 = 40.8 dB
ABM1 comp = -14.8 dB A/m
BWC Factor = 0.0105036 dB
Location: -5, 3, 363.7 mm

Y (Radial) 16x24 scan:

0 dB = 1.00A/m

Z (AXIAL) MEASUREMENT: CDMA 1900 Channel 25

Equipment Setting:

DUT: SCP-2700; Type: Cellular Phone ; Serial Number: 0450;   **Date:** 12/14/2008
Communication System: CDMA; Frequency: 1850 MHz;Duty Cycle: 1:1
Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH25/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -6.44 dB A/m
BWC Factor = 0.0163141 dB
Location: -3, -5, 363.7 mm

Scans CH25/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -4.25 dB A/m
BWC Factor = 0.0163141 dB
Location: 3, -5, 363.7 mm

Point meas,TCoil on CH25/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -4.11 dB A/m
BWC Factor = 0.0155338 dB
Location: -1, -5, 363.7 mm

Point meas,TCoil on CH25/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -40.6 dB A/m
Location: -1, -5, 363.7 mm

Point meas,TCoil on CH25/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):
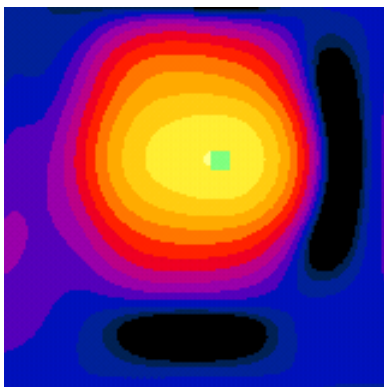Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1/ABM2 = 36.5 dB
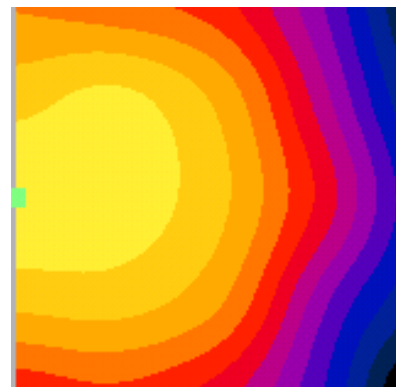ABM1 comp = -4.11 dB A/m
BWC Factor = 0.0155338 dB
Location: -1, -5, 363.7 mm

Z (axial) rough 50x50 scan: **Z (axial) 16x16scan:**

0 dB = 1.00A/m   0 dB = 1.00A/m

X RADIAL MEASUREMENT: CDMA 1900 Channel 25

Equipment Setting:

DUT: SCP-2700;   Type: Cellular Phone ;   Serial Number: 0450;   **Date:** 12/14/2008
Communication System: CDMA; Frequency: 1850 MHz;Duty Cycle: 1:1
Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH25/x (longitudinal) 24 x 16/ABM Interpolated Signal(x,y,z) (61x41x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -13.0 dB A/m
BWC Factor = 0.0163141 dB
Location: 7.4, -5, 363.7 mm

Point meas,TCoil on CH25/x (longitudinal) at max x/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -13.8 dB A/m
BWC Factor = 0.0155338 dB
Location: 7, -9, 363.7 mm

Point meas,TCoil on CH25/x (longitudinal) at max x/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -49.4 dB A/m
Location: 7, -9, 363.7 mm

Point meas,TCoil on CH25/x (longitudinal) at max x/ABM SNR(x,y,z) (1x1x1):
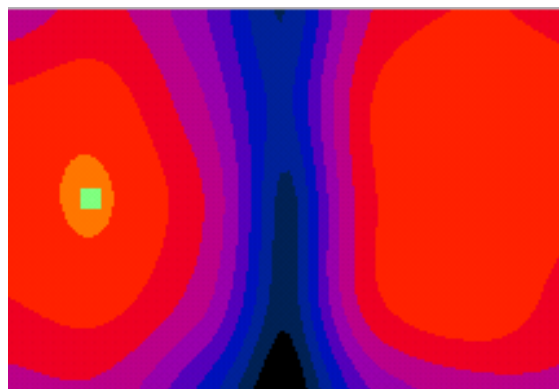Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1/ABM2 = 35.6 dB
ABM1 comp = -13.8 dB A/m
BWC Factor = 0.0155338 dB
Location: 7, -9, 363.7 mm

X (Radial) 24x16 scan:

0 dB = 1.00A/m

Y RADIAL MEASUREMENT: CDMA 1900 Channel 25

Equipment Setting:

DUT: SCP-2700;   Type: Cellular Phone ;   Serial Number: 0450;   **Date:** 12/14/2008
Communication System: CDMA; Frequency: 1850 MHz;Duty Cycle: 1:1
Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH25/y (transversal) 16 x 24/ABM
Interpolated Signal(x,y,z) (41x61x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -11.9 dB A/m
BWC Factor = 0.0163141 dB
Location: 1.4, -13, 363.7 mm

Point meas,TCoil on CH25/y (transversal) at max
y/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -15.6 dB A/m
BWC Factor = 0.0155338 dB
Location: -5, 7, 363.7 mm

Point meas,TCoil on CH25/y (transversal) at max
y/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -56.9 dB A/m
Location: -5, 7, 363.7 mm

Point meas,TCoil on CH25/y (transversal) at max
y/ABM SNR(x,y,z) (1x1x1):
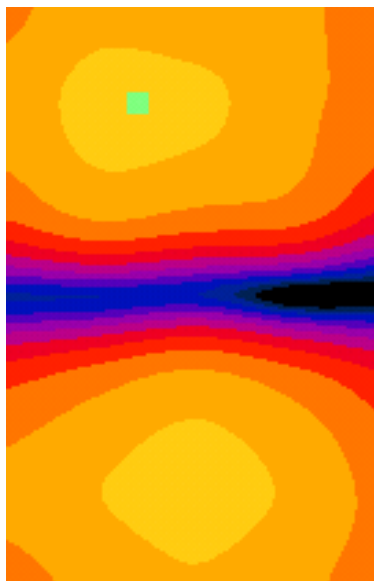Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1/ABM2 = 41.3 dB
ABM1 comp = -15.6 dB A/m
BWC Factor = 0.0155338 dB
Location: -5, 7, 363.7 mm

Y (Radial) 16x24 scan:

0 dB = 1.00A/m

Z (AXIAL) MEASUREMENT: CDMA 1900 Channel 600

Equipment Setting:

DUT: SCP-2700;   Type: Cellular Phone ;   Serial Number: 0450;   **Date:** 12/14/2008
Communication System: CDMA; Frequency: 1880 MHz;Duty Cycle: 1:1
Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH600/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -5.65 dB A/m
BWC Factor = 0.0158807 dB
Location: -1, -5, 363.7 mm

Scans CH600/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -4.25 dB A/m
BWC Factor = 0.0158807 dB
Location: -0.2, -5.4, 363.7 mm

Point meas,TCoil on CH600/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -4.70 dB A/m
BWC Factor = 0.0158807 dB
Location: -1, -5, 363.7 mm

Point meas,TCoil on CH600/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -41.8 dB A/m
Location: -1, -5, 363.7 mm

Point meas,TCoil on CH600/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):
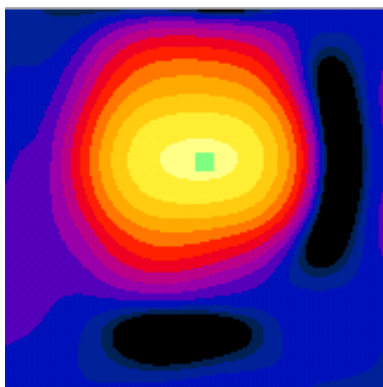Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1/ABM2 = 37.1 dB
ABM1 comp = -4.70 dB A/m
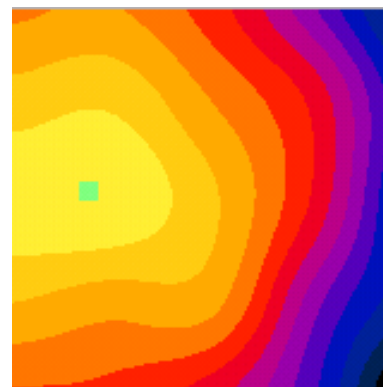BWC Factor = 0.0158807 dB
Location: -1, -5, 363.7 mm

Z (axial) rough 50x50 scan:

0 dB = 1.00A/m

Z (axial) 16x16scan:

0 dB = 1.00A/m

X RADIAL MEASUREMENT: CDMA 1900 Channel 600

Equipment Setting:

DUT: SCP-2700; Type: Cellular Phone ; Serial Number: 0450;   **Date:** 12/14/2008
Communication System: CDMA; Frequency: 1880 MHz;Duty Cycle: 1:1
Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH600/x (longitudinal) 24 x 16/ABM Interpolated Signal(x,y,z) (61x41x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -13.3 dB A/m
BWC Factor = 0.0158807 dB
Location: 7.4, -5, 363.7 mm

Point meas,TCoil on CH600/x (longitudinal) at max x/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -14.0 dB A/m
BWC Factor = 0.0158807 dB
Location: -5, -9, 363.7 mm

Point meas,TCoil on CH600/x (longitudinal) at max x/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -49.4 dB A/m
Location: -5, -9, 363.7 mm

Point meas,TCoil on CH600/x (longitudinal) at max x/ABM SNR(x,y,z) (1x1x1):
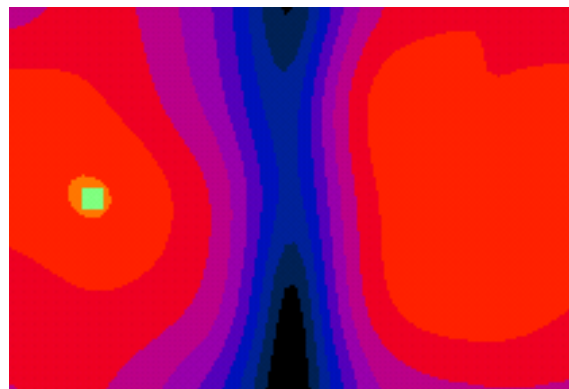Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1/ABM2 = 35.4 dB
ABM1 comp = -14.0 dB A/m
BWC Factor = 0.0158807 dB
Location: -5, -9, 363.7 mm

X (Radial) 24x16 scan:

0 dB = 1.00A/m

Y RADIAL MEASUREMENT: CDMA 1900 Channel 600

Equipment Setting:

DUT: SCP-2700;   Type: Cellular Phone ;   Serial Number: 0450;   **Date:** 12/14/2008
Communication System: CDMA; Frequency: 1880 MHz;Duty Cycle: 1:1
Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH600/y (transversal) 16 x 24/ABM
Interpolated Signal(x,y,z) (41x61x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -12.5 dB A/m
BWC Factor = 0.0158807 dB
Location: 2.2, -13, 363.7 mm

Point meas,TCoil on CH600/y (transversal) at max
y/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -15.1 dB A/m
BWC Factor = 0.0158807 dB
Location: -5, 7, 363.7 mm

Point meas,TCoil on CH600/y (transversal) at max
y/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -56.8 dB A/m
Location: -5, 7, 363.7 mm

Point meas,TCoil on CH600/y (transversal) at max
y/ABM SNR(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
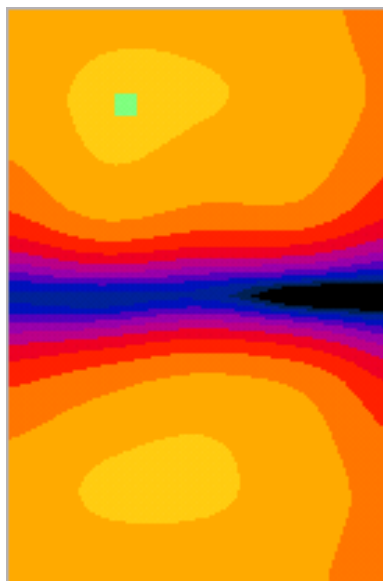**Cursor:**
ABM1/ABM2 = 41.7 dB
ABM1 comp = -15.1 dB A/m
BWC Factor = 0.0158807 dB
Location: -5, 7, 363.7 mm

Y (Radial) 16x24 scan:

0 dB = 1.00A/m

Z (AXIAL) MEASUREMENT: CDMA 1900 Channel 1175

Equipment Setting:

DUT: SCP-2700;   Type: Cellular Phone ;   Serial Number: 0450;   **Date:** 12/14/2008
Communication System: CDMA; Frequency: 1910 MHz;Duty Cycle: 1:1
Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH1175/z (axial) rough 50 x 50/ABM Interpolated Signal(x,y,z) (51x51x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -5.52 dB A/m
BWC Factor = 0.0159674 dB
Location: 0, -5, 363.7 mm

Scans CH1175/z (axial) 16 x 16/ABM Interpolated Signal(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -2.91 dB A/m
BWC Factor = 0.0159674 dB
Location: -0.6, -5, 363.7 mm

Point meas,TCoil on CH1175/z (axial) at max z/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -3.50 dB A/m
BWC Factor = 0.0148402 dB
Location: -1, -5, 363.7 mm

Point meas,TCoil on CH1175/z (axial) at max z/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -40.9 dB A/m
Location: -1, -5, 363.7 mm

Point meas,TCoil on CH1175/z (axial) at max z/ABM SNR(x,y,z) (1x1x1):
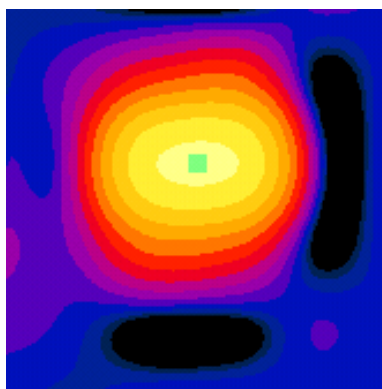Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1/ABM2 = 37.4 dB
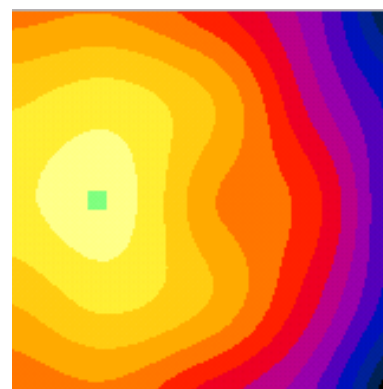ABM1 comp = -3.50 dB A/m
BWC Factor = 0.0148402 dB
Location: -1, -5, 363.7 mm

Z (axial) rough 50x50 scan:

0 dB = 1.00A/m

Z (axial) 16x16scan:

0 dB = 1.00A/m

X RADIAL MEASUREMENT: CDMA 1900 Channel 1175

Equipment Setting:

DUT: SCP-2700;   Type: Cellular Phone ;   Serial Number: 0450;   **Date:** 12/14/2008
Communication System: CDMA; Frequency: 1910 MHz;Duty Cycle: 1:1
Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH1175/x (longitudinal) 24 x 16/ABM Interpolated Signal(x,y,z) (61x41x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -11.5 dB A/m
BWC Factor = 0.0159674 dB
Location: -9, -5, 363.7 mm

Point meas,TCoil on CH1175/x (longitudinal) at max x/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -16.3 dB A/m
BWC Factor = 0.0148402 dB
Location: 11, -9, 363.7 mm

Point meas,TCoil on CH1175/x (longitudinal) at max x/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -49.2 dB A/m
Location: 11, -9, 363.7 mm

Point meas,TCoil on CH1175/x (longitudinal) at max x/ABM SNR(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
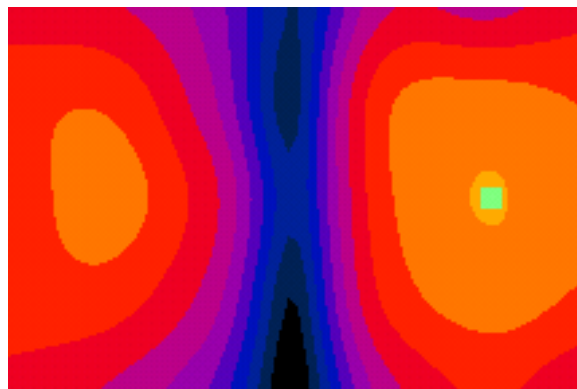**Cursor:**
ABM1/ABM2 = 32.9 dB
ABM1 comp = -16.3 dB A/m
BWC Factor = 0.0148402 dB
Location: 11, -9, 363.7 mm

X (Radial) 24x16 scan:

0 dB = 1.00A/m

Y RADIAL MEASUREMENT: CDMA 1900 Channel 1175

Equipment Setting:

DUT: SCP-2700;   Type: Cellular Phone ;   Serial Number: 0450;   **Date:** 12/14/2008
Communication System: CDMA; Frequency: 1910 MHz;Duty Cycle: 1:1
Medium parameters used: σ = 0 mho/m, $ε_r$ = 1; ρ = 0 kg/m^3
Phantom section: AMB with Coil Section
DASY4 Configuration:
- Probe: AM1DV2 - 1045; ; Calibrated: 9/18/2008
- Sensor-Surface: 0mm (Fix Surface)
- Electronics: DAE4 Sn530; Calibrated: 4/15/2008
- Phantom: HAC Test Arch with Coil; Type: SD HAC P01 BA; Serial: 100x
- Measurement SW: DASY4, V4.7 Build 71; Postprocessing SW: SEMCAD, V1.8 Build 184

Scans CH1175/y (transversal) 16 x 24/ABM Interpolated Signal(x,y,z) (41x61x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 = -12.1 dB A/m
BWC Factor = 0.0159674 dB
Location: -1.4, -12.6, 363.7 mm

Point meas,TCoil on CH1175/y (transversal) at max y/ABM Signal(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1 comp = -15.9 dB A/m
BWC Factor = 0.0148402 dB
Location: -1, 7, 363.7 mm

Point meas,TCoil on CH1175/y (transversal) at max y/ABM Noise(x,y,z) (1x1x1):
Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM2 = -54.6 dB A/m
Location: -1, 7, 363.7 mm

Point meas,TCoil on CH1175/y (transversal) at max y/ABM SNR(x,y,z) (1x1x1):
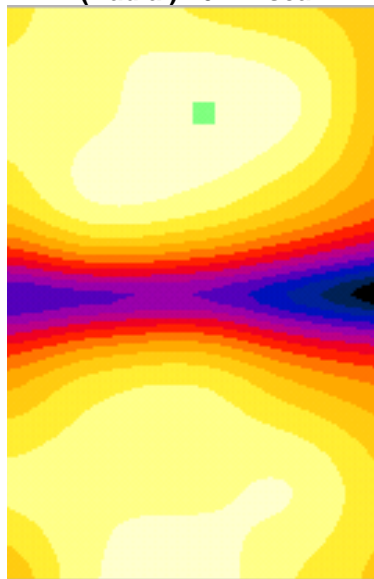Measurement grid: dx=10mm, dy=10mm
Cursor:
ABM1/ABM2 = 38.8 dB
ABM1 comp = -15.9 dB A/m
BWC Factor = 0.0148402 dB
Location: -1, 7, 363.7 mm

Y (Radial) 16x24 scan:

0 dB = 1.00A/m